



DesignCon Keynotes Selected to Inspire & Challenge 2017 Audience

Representatives from Microsoft, Ansoft Inc. & NSF Center for Advanced Electronics through Machine Learning (CAEML) will take the Keynote Stage in Santa Clara, CA

NEWS PROVIDED BY

DesignCon →

Nov 15, 2016, 09:00 ET

SAN FRANCISCO, Nov. 15, 2016 /PRNewswire/ -- DesignCon, the premier conference for chip, board, and systems design engineers, today announces its 2017 keynote lineup. This year's keynote program will offer exciting and insightful presentations covering connected cars and the Internet of Things (IoT), signal integrity and electromagnetic field simulation, and machine learning and artificial intelligence presented by top leaders from Microsoft, Ansoft Inc. & NSF Center for Advanced Electronics through Machine Learning (CAEML).

DesignCon 2017 will return to the Santa Clara Convention Center in Santa Clara, CA, January 31 – February 2. For more information and to register, please visit: designcon.com/santaclara/passes-pricing.

DesignCon 2017 Keynote Lineup:

Zoltan Cendes – Founder, Ansoft Inc.

Zoltan is the founder of Ansoft Corporation – he previously served on the ANSYS Board of Directors and as President of Ansoft LLC. He has made significant contributions in the area of finite element modeling of electromagnetic fields. In particular, he and his coworkers introduced a number of new technologies in numerical electromagnetics. His original research in these areas made possible many of Ansoft's products, including HFSS™. Zoltan also developed electromagnetic field simulation codes for the General Electric Corporation, and in 1980 he was appointed Associate Professor of Electrical Engineering at McGill University, Montreal, Canada. In 1982, he joined the faculty of the Electrical and Computer Engineering Department at Carnegie Mellon University, Pittsburgh, PA, where he was a Professor until 1996. Zoltan is a Life Fellow of the IEEE, has served on the Editorial Board of IEEE Spectrum, on the International Steering Committee of the COMPUMAG Conference and as an IEEE Antennas and Propagation Society Distinguished Lecturer.

Keynote: *Turning Signal Integrity Simulation Inside Out:* Zoltan will share his insights on how modern simulation has placed physics-based solvers in the foreground, supported by circuit and system simulation.

Elyse Rosenbaum – Director, NSF Center for Advanced Electronics through Machine Learning (CAEML)

Elyse is the Melvin and Anne Louise Hassebrock Professor in Electrical and Computer Engineering at the University of Illinois at Urbana-Champaign and is currently the director of the NSF Center for Advanced Electronics through Machine Learning (CAEML). Her present research interests range from component and system-level ESD reliability, transient latch-up, ESD-robust high-speed I/O circuit design and more. Additionally, Elyse has authored/co-authored over 150 technical papers, presented tutorials on reliability physics at the International Reliability Physics Symposium, the EOS/ESD Symposium, and the RFIC Symposium, and she has given invited lectures at many universities and industrial laboratories. From 2001 through 2011 she was an editor for IEEE Transactions on Device

and Materials Reliability and is currently an editor for IEEE Transactions on Electron Devices. Elyse was the technical program chair for the 2016 International Reliability Physics Symposium.

Keynote: Machine Learning: An Enabling Technique for Electronics Modeling and Design Optimization: Elyse will explore how behavior modeling, strengthened by machine learning, can provide the solution.

Doug Seven – Connected Things Lead, Azure IoT, Microsoft

Doug is responsible for the development of Azure IoT services and reference solutions specifically focusing on connected, mobile things. He has spent 17 years in and around Microsoft, including two departures from Microsoft to work in the start-up ecosystem, developing solutions to enable software developers to be more productive. In the past several years, Doug has focused on supporting major companies innovate in the area of the Internet of Things. Through his work with automotive companies on their connected car visions, he has developed a passion for connected vehicles and the future of autonomous vehicles.

Keynote: The Internet of Things That Move – Connected Cars & Beyond: Doug will explore Microsoft's view of the connected car space and describes how industry players can evolve their offerings from providing simple connectivity to enabling full autonomy. He will show how coming advances can inspire new business models and driver experiences that also have a positive impact on the relevant public infrastructure.

Learn more about the 2017 DesignCon Keynotes here: designcon.com/santaclara/conference/keynotes

"Our mission each year is to provide the DesignCon audience with programming specific to their professional needs and interests – we believe this Keynote lineup is the perfect reflection of this mission," said Naomi Price, DesignCon Conference Content Director. "Each

of these presentations will offer insight and inspiration spanning multiple industry relevant topics. Our keynote speakers bring with them a wide range of experiences and we're thrilled with the arsenal of valuable information they have prepared to share with our attendees."

DesignCon 2017

DesignCon serves the high-speed communications and semiconductor communities offering state-of-the-art design methodologies, applications, technologies, and unparalleled networking opportunities. This year's event will offer a range of in-depth sessions covering the hottest industry trends in addition to an Expo Floor filled with leading solution providers displaying their latest innovations.

Apply for a Media Pass here: designcon.tech.ubm.com/2017/registrations/Media

Follow DesignCon online:

Facebook: facebook.com/DesignCon

Twitter: [@UBMDesignCon](https://twitter.com/UBMDesignCon)

Linkedin: linkedin.com/groups/1272607

Flickr: flickr.com/photos/designcon

About DesignCon

DesignCon is the world's premier conference for chip, board, and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board, and systems designers in the country. This three-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: designcon.com. DesignCon is organized by UBM Americas, a part of UBM plc (UBM.L), an Events First marketing and communications services business. For more information, visit ubmamericas.com.

SOURCE DesignCon

Related Links

<http://www.designcon.com>